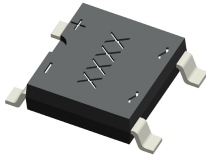


ABS05 THRU ABS10



ABS

FEATURES

- Glass passivated chip junction
- Ideal for printed circuit board
- High forward surge capability
- Solder dip 260 °C, 40 s

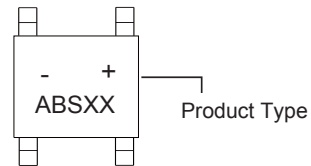
PRIMARY CHARACTERISTICS

I _{F(AV)}	0.8 A
V _{RRM}	50 V THRU 1000 V
I _{FSM}	30A
I _R	5 μA
V _F	1.1V
T _J max.	150 °C

MECHANICAL DATA

Case: ABS molded plastic body
Polarity: Symbol molded on body
Mounting Position: Any

Part Marking System



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25 C ambient temperature unless otherwise specified.
 Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

CHARACTERISTICS	SYMBOL	ABS05	ABS1	ABS2	ABS4	ABS6	ABS8	ABS10	UNIT
Maximum Recurrent Peak Reverse Voltage	VRRM	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	VRMS	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	VDC	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current @T _A =40 °C	I(AV)	0.8							A
Peak Forward Surge Current 8.3ms Single Half Sine-Wave Super Imposed on Rated Load(JEDEC Method)	IFSM	30							A
Peak Forward Voltage at 0.8A DC	VF	1.1							V
Maximum DC Reverse Current at Rated DC Blocking Voltage @T _J =25°C @T _J =125°C	IR	5.0 500							μA
Operating Temperature Range	TJ	-55 to +150							°C
Storage Temperature Range	TSTG	-55 to +150							°C

TVS
Rectifiers
SKY
Zener
Switching
DIAC
Bridge

Ratings and Characteristic Curves ($T_A=25^\circ\text{C}$ unless otherwise noted)

FIG. 1- FORWARD CURRENT DERATING CURVE

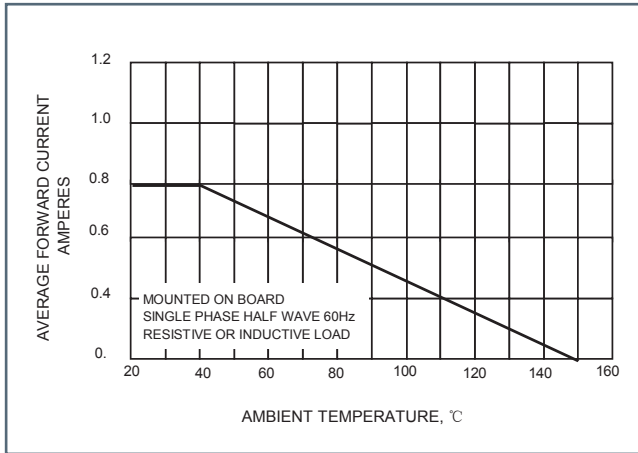


FIG. 2-MAXIMUM NON-REPETITIVE SURGE CURRENT

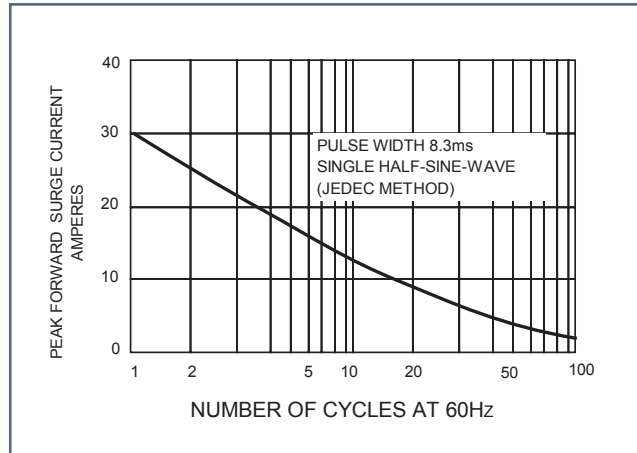


FIG. 3-TYPICAL REVERSE CHARACTERISTICS

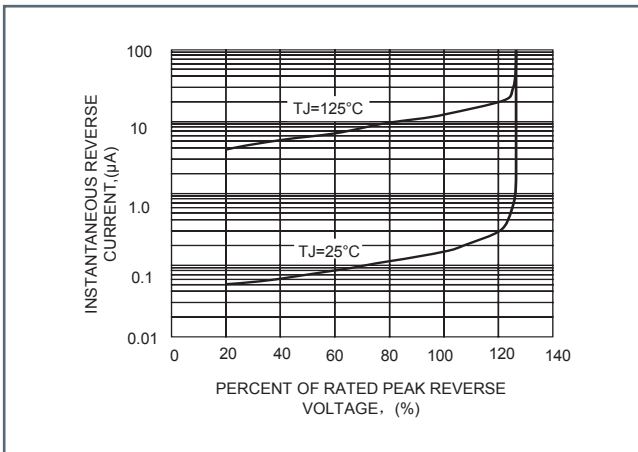
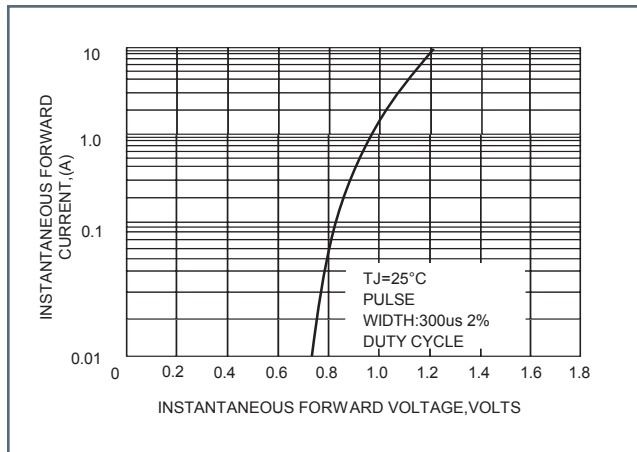
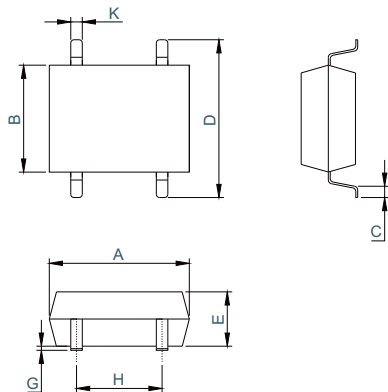


FIG. 4-TYPICAL FORWARD CHARACTERISTICS



Dimensions

ABS



DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	0.191	0.213	4.85	5.40	
B	0.165	0.181	4.20	4.60	
C	0.012	0.028	0.30	0.70	
D	0.236	0.264	6.00	6.70	
E	0.047	0.059	1.20	1.50	
G	—	0.008	—	0.20	
H	0.154	0.161	3.90	4.10	
K	0.024	0.028	0.60	0.70	